

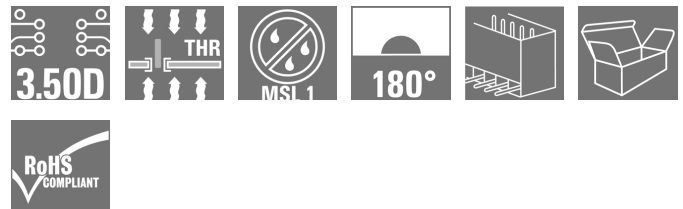
S2L-SMT 3.50/08/180G 3.5SN BK BX TB**Weidmüller Interface GmbH & Co. KG**

Klingenbergstraße 26

D-32758 Detmold

Germany

www.weidmueller.com

Product image

Similar to illustration

High-temperature-resistant, double-row pin header for all common soldering methods. Optimised for automatic assembly. Packed in box or tape. Solder pin 3.2 mm long, suitable for reflow and wave soldering. The male connectors provide space for labelling and can be coded.

General ordering data

Version	PCB plug-in connector, male header, closed side, THT/THR solder connection, 3.50 mm, Number of poles: 8, 180°, Solder pin length (l): 3.5 mm, tinned, black, Box
Order No.	1288810000
Type	S2L-SMT 3.50/08/180G 3.5SN BK BX TB
GTIN (EAN)	4050118080223
Qty.	120 pc(s).
Product data	IEC: 160 V / 10 A UL: 150 V / 10 A
Packaging	Box

Creation date March 23, 2021 2:26:33 PM CET

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Technical data

Dimensions and weights

Depth	10.8 mm	Depth (inches)	0.425 inch
Height	14.3 mm	Height (inches)	0.563 inch
Height of lowest version	14.2 mm	Net weight	0.93 g
Width	15.4 mm	Width (inches)	0.606 inch

System specifications

Product family	OMNIMATE Signal - series B2L/S2L 3.50 - 2-row	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	3.5 mm
Pitch in inches (P)	0.138 inch	Outgoing elbow	180°
Number of poles	8	Number of solder pins per pole	1
Solder pin length (l)	3.5 mm	Solder pin dimensions	d = 1.0 mm, Octagonal
Solder eyelet hole diameter (D)	1.3 mm	Solder eyelet hole diameter tolerance (D) + 0,1 mm	
Outside diameter of solder pad	2.1 mm	Template aperture diameter	1.9 mm
L1 in mm	10.5 mm	L1 in inches	0.413 inch
Number of rows	2	Pin series quantity	2
Touch-safe protection acc. to DIN VDE 57 106	Safe from back-of-hand touch	Touch-safe protection acc. to DIN VDE 0470	IP 10
Can be coded	Yes	Plugging cycles	25
Plugging force/pole, max.	3 N	Pulling force/pole, max.	6 N

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIb
Comparative Tracking Index (CTI)	≥ 175	Insulation strength	≥ 10 ⁸ Ω
Moisture Level (MSL)	1	UL 94 flammability rating	V-0
Contact material	Copper alloy	Contact surface	tinned
Layer structure of solder connection	2...3 µm Ni / 5...7 µm Sn glossy	Layer structure of plug contact	2...5 µm Sn / 1...3 µm Ni
Storage temperature, min.	-40 °C	Storage temperature, max.	70 °C
Operating temperature, min.	-50 °C	Operating temperature, max.	100 °C
Temperature range, installation, min.	-30 °C	Temperature range, installation, max.	100 °C

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	10 A
Rated current, max. number of poles (Tu=20°C)	10 A	Rated current, min. number of poles (Tu=40°C)	9 A
Rated current, max. number of poles (Tu=40°C)	8.5 A	Rated voltage for surge voltage class / pollution degree II/2	160 V
Rated voltage for surge voltage class / pollution degree III/2	125 V	Rated voltage for surge voltage class / pollution degree III/3	50 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	1.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	1.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 77 A

Rated data acc. to CSA

Rated voltage (Use group B / CSA)	50 V	Rated voltage (Use group C / CSA)	50 V
Rated voltage (Use group D / CSA)	150 V	Rated current (Use group B / CSA)	5 A
Rated current (Use group C / CSA)	9.5 A	Rated current (Use group D / CSA)	9.5 A

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Technical data**Rated data acc. to UL 1059**

Institute (UR)



Certificate No. (UR)

E60693

Rated voltage (Use group B / UL 1059) 150 V

Rated current (Use group B / UL 1059) 10 A

Reference to approval values

Specifications are maximum values, details - see approval certificate.

Packing

Packaging

Box

VPE length

35 mm

VPE width

90 mm

VPE height

125 mm

Important note

IPC conformity

Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.

Notes

- Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months

Approvals

Approvals



ROHS

Conform

UL File Number Search

E60693

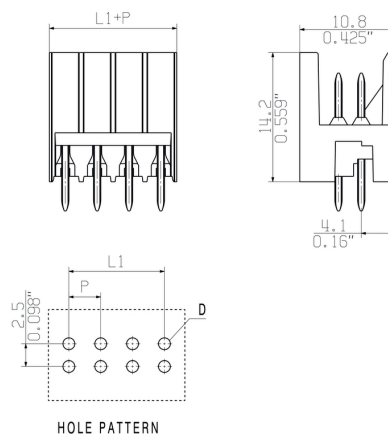
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Drawings**Product image**

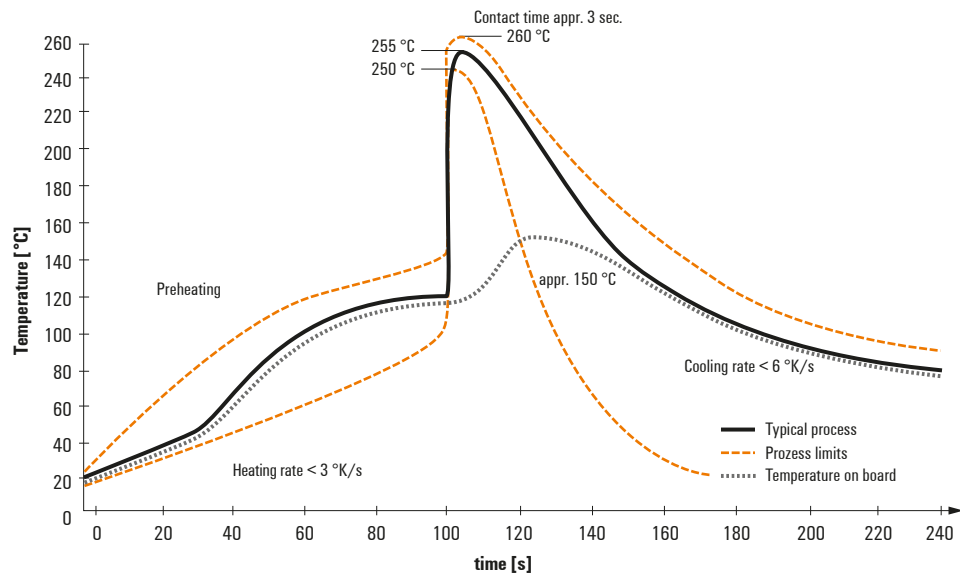
Similar to illustration

Dimensional drawing

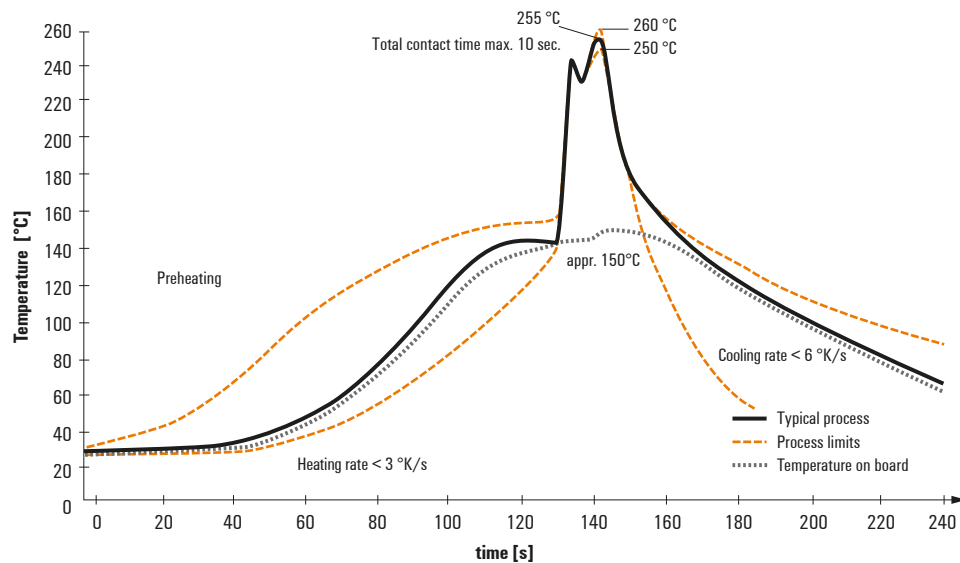
Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 16

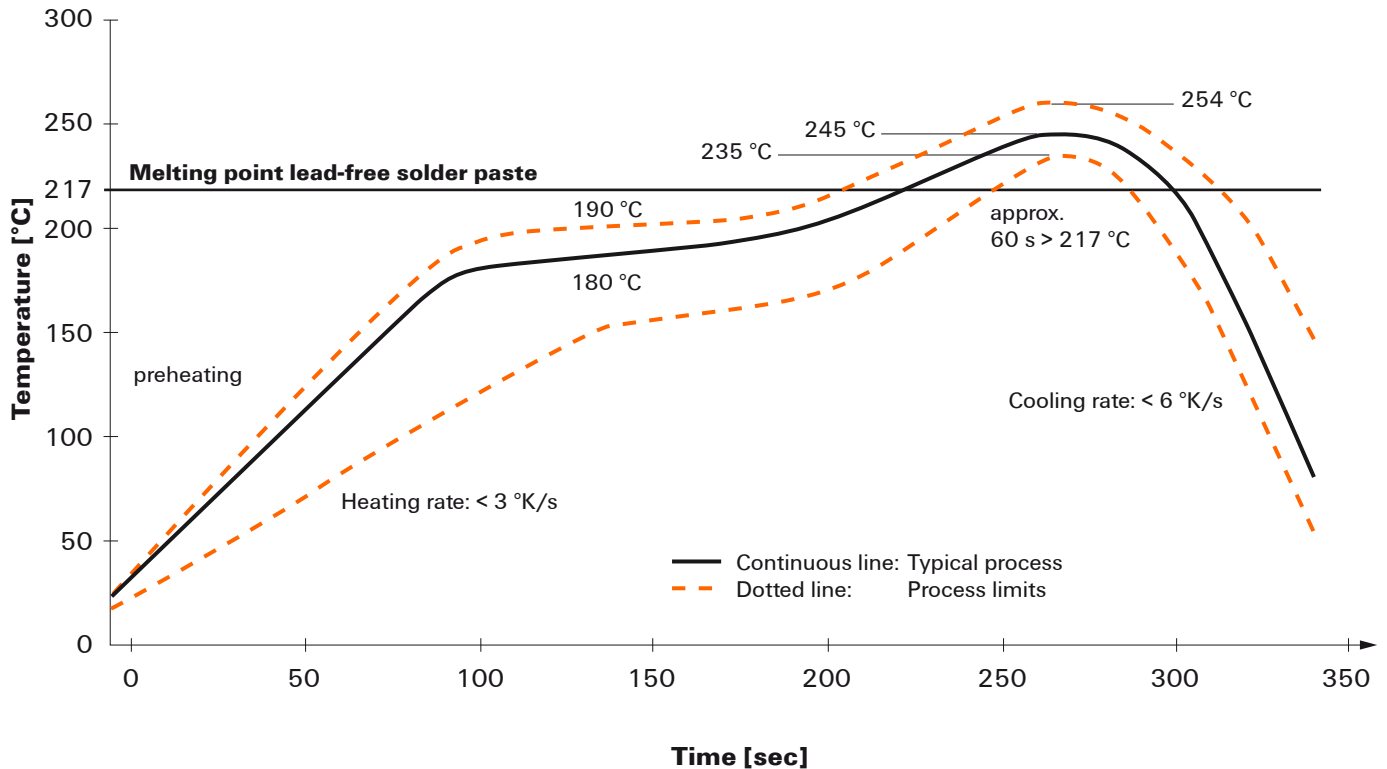
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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.